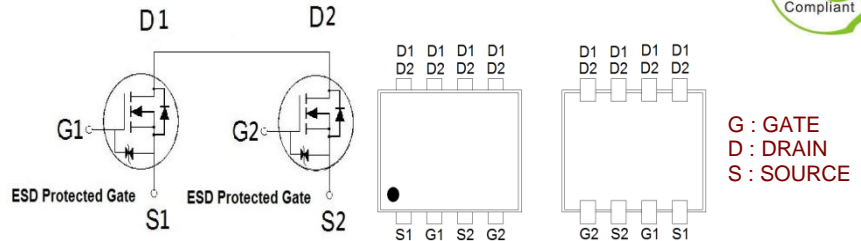




PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
20V	11.8mΩ	10.5A



G : GATE
D : DRAIN
S : SOURCE

ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ °C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	20	V
Gate-Source Voltage		V_{GS}	±10	V
Continuous Drain Current ²	$T_A = 25\text{ °C}$	I_D	10.5	A
	$T_A = 70\text{ °C}$		8.4	
Pulsed Drain Current ^{1,3}		I_{DM}	53	
Avalanche Current		I_{AS}	22	
Avalanche Energy	$L = 0.1\text{mH}$	E_{AS}	24	mJ
Power Dissipation ³	$T_A = 25\text{ °C}$	P_D	2.1	W
	$T_A = 70\text{ °C}$		1.3	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE		SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient	$t \leq 10\text{s}$	$R_{\theta JA}$		58	°C / W
Junction-to-Ambient	Steady-State	$R_{\theta JA}$		73	

¹Pulse width limited by maximum junction temperature.

²Package limitation current is 7A.

³The Power dissipation is based on $R_{\theta JA} t \leq 10\text{s}$ value.

ELECTRICAL CHARACTERISTICS ($T_J = 25\text{ °C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	20			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	0.35	0.7	1	V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{V}, V_{GS} = \pm 8\text{V}$			±30	uA

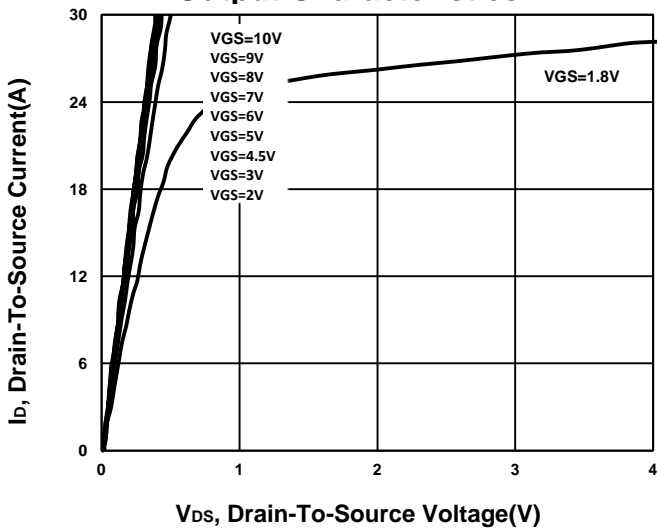
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 16V, V_{GS} = 0V$			1	μA
		$V_{DS} = 10V, V_{GS} = 0V, T_J = 70\text{ }^\circ C$			10	
Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = 2.5V, I_D = 3A$	8.5	13	20	$m\Omega$
		$V_{GS} = 3.1V, I_D = 3A$	7.8	11.5	15.3	
		$V_{GS} = 3.8V, I_D = 3A$	7.2	10.6	12.9	
		$V_{GS} = 4.5V, I_D = 3A$	7.1	10	11.8	
Forward Transconductance ¹	g_{fs}	$V_{DS} = 5V, I_D = 3A$		40		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 10V, f = 1MHz$		1133		pF
Output Capacitance	C_{oss}			214		
Reverse Transfer Capacitance	C_{rss}			168		
Gate Resistance	R_g	$V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$		1.5		Ω
Total Gate Charge ²	Q_g	$V_{DS} = 10V, V_{GS} = 4.5V,$ $I_D = 3A$		17.4		nC
Gate-Source Charge ²	Q_{gs}			1.1		
Gate-Drain Charge ²	Q_{gd}			5.1		
Turn-On Delay Time ²	$t_{d(on)}$	$V_{DS} = 10V,$ $I_D \cong 3A, V_{GS} = 4.5V, R_G = 6\ \Omega$		24		nS
Rise Time ²	t_r			32		
Turn-Off Delay Time ²	$t_{d(off)}$			66		
Fall Time ²	t_f			35		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS						
Continuous Current	I_S				1.7	A
Forward Voltage ¹	V_{SD}	$I_F = 3A, V_{GS} = 0V$			1.2	V
Reverse Recovery Time	t_{rr}	$I_F = 3A, di_F/dt = 100A / \mu S$		14		nS
Reverse Recovery Charge	Q_{rr}			5.4		nC

¹Pulse test : Pulse Width $\leq 300\ \mu sec$, Duty Cycle $\leq 2\%$.

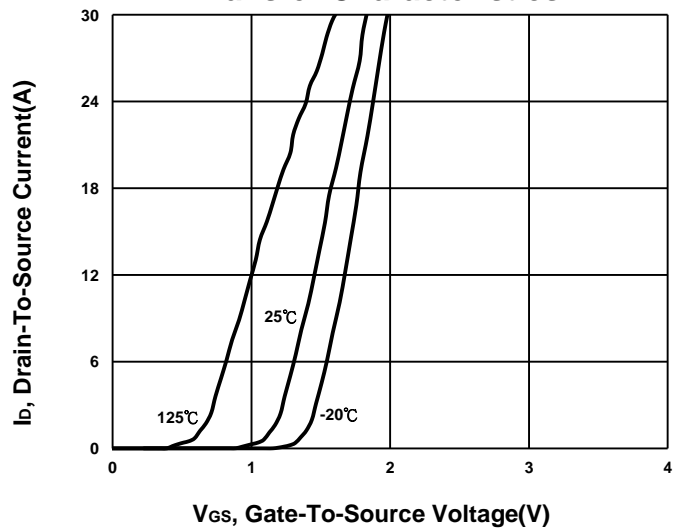
²Independent of operating temperature.

³Pulse width limited by maximum junction temperature.

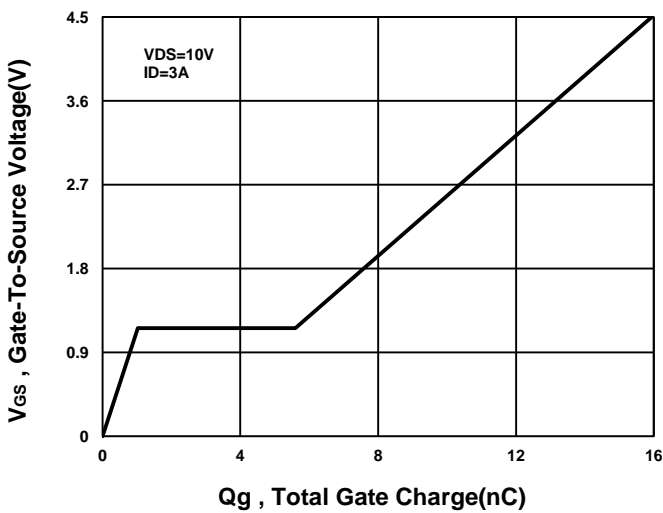
Output Characteristics



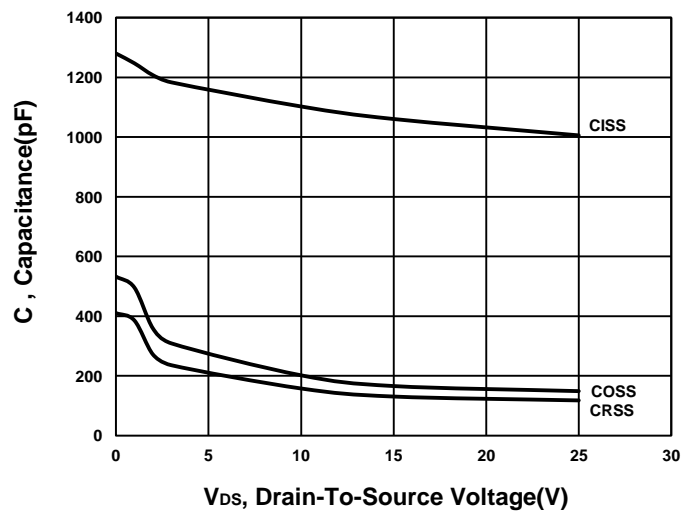
Transfer Characteristics



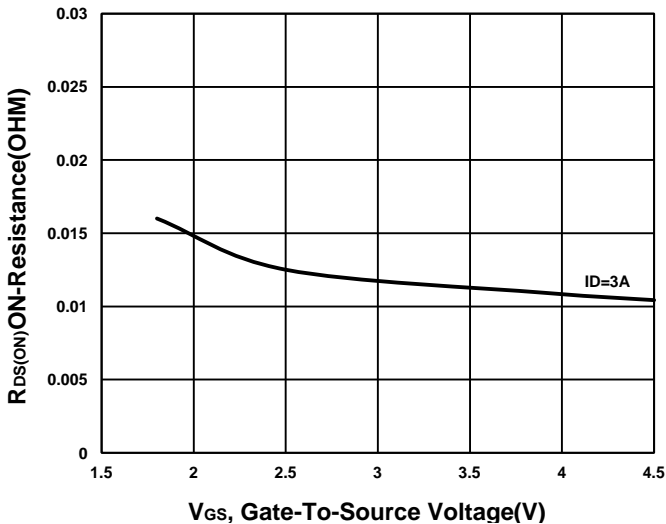
Gate charge Characteristics



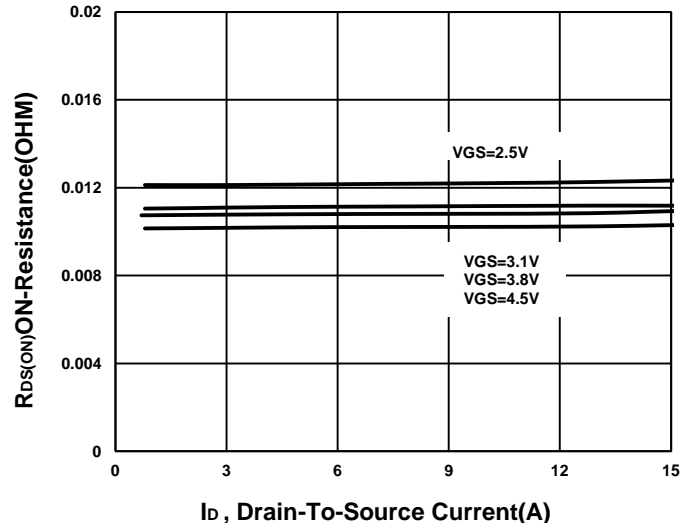
Capacitance Characteristic



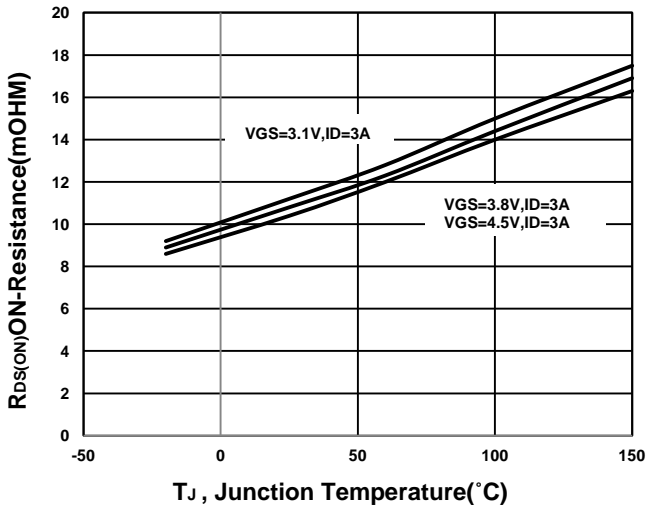
On-Resistance VS Gate-To-Source



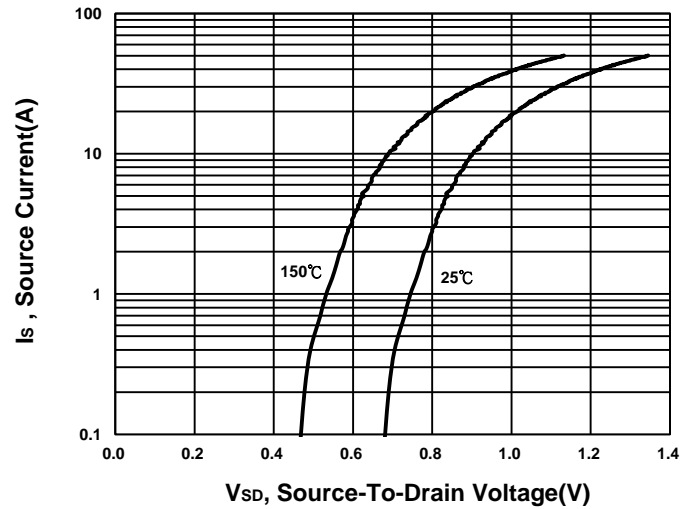
On-Resistance VS Drain Current



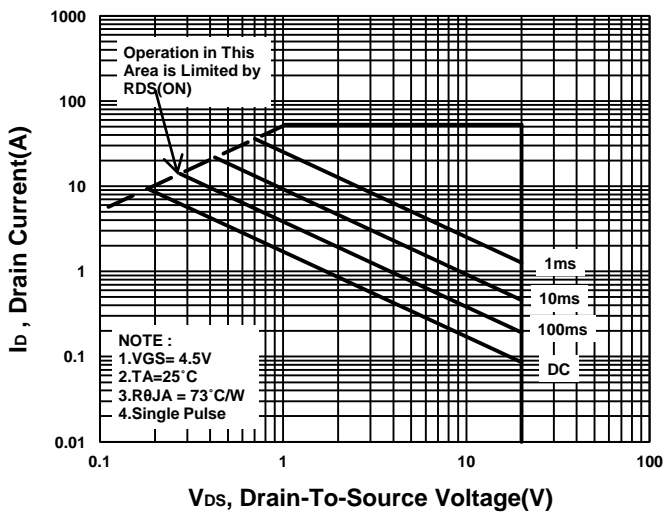
On-Resistance VS Temperature



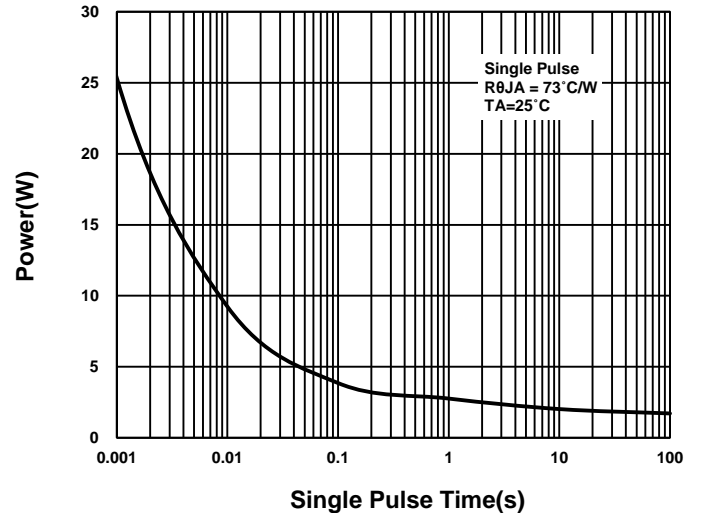
Source-Drain Diode Forward Voltage



Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve

